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# Single Non-Inverting Buffer with Open Drain Output

## MC74VHC1G07, MC74VHC1GT07

The MC74VHC1G07 / MC74VHC1GT07 is a single non-inverting buffer with open drain output in tiny footprint packages. The MC74VHC1G07 has CMOS-level input thresholds while the MC74VHC1GT07 has TTL-level input thresholds.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. The output structures also provide protection when  $V_{CC} = 0$  V and when the output voltage exceeds  $V_{CC}$ . These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

### Features

- Designed for 2.0 V to 5.5 V  $V_{CC}$  Operation
- 3.5 ns  $t_{PD}$  at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- $I_{OFF}$  Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

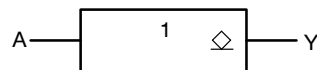


Figure 1. Logic Symbol



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| MARKING DIAGRAMS |                                    |  |
|------------------|------------------------------------|--|
|                  | SC-88A<br>DF SUFFIX<br>CASE 419A   |  |
|                  | SC-74A<br>DBV SUFFIX<br>CASE 318BQ |  |
|                  | TSOP-5<br>DT SUFFIX<br>CASE 483    |  |
|                  | SOT-553<br>XV5 SUFFIX<br>CASE 463B |  |
|                  | SOT-953<br>P5 SUFFIX<br>CASE 527AE |  |
|                  | UDFN6<br>1.45 x 1.0<br>CASE 517AQ  |  |
|                  | UDFN6<br>1.2 x 1.0<br>CASE 517AA   |  |
|                  | UDFN6<br>1.0 x 1.0<br>CASE 517BX   |  |

XX = Specific Device Code  
 M = Date Code\*  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

# MC74VHC1G07, MC74VHC1GT07

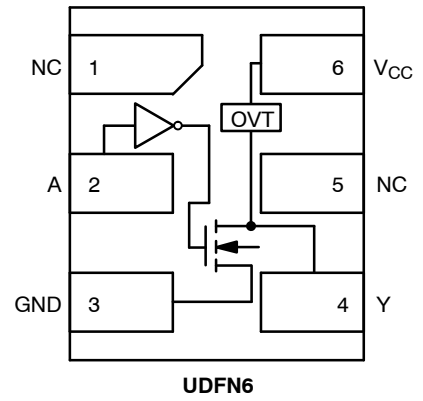
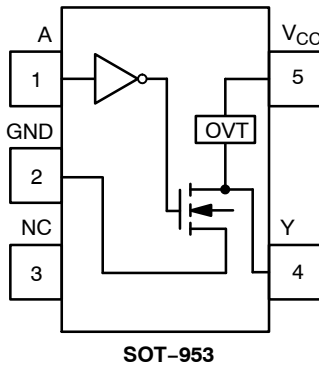
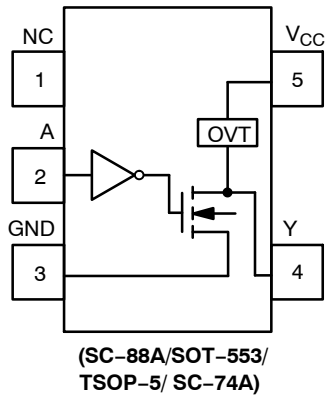


Figure 2. Pinout (Top View)

## PIN ASSIGNMENT

(SC-88A/SOT-553/ TSOP-5/SC-74A)

| Pin | Function        |
|-----|-----------------|
| 1   | NC              |
| 2   | A               |
| 3   | GND             |
| 4   | Y               |
| 5   | V <sub>CC</sub> |

## PIN ASSIGNMENT (SOT-953)

| Pin | Function        |
|-----|-----------------|
| 1   | A               |
| 2   | GND             |
| 3   | NC              |
| 4   | Y               |
| 5   | V <sub>CC</sub> |

## PIN ASSIGNMENT (UDFN)

| Pin | Function        |
|-----|-----------------|
| 1   | NC              |
| 2   | A               |
| 3   | GND             |
| 4   | Y               |
| 5   | NC              |
| 6   | V <sub>CC</sub> |

## FUNCTION TABLE

| A Input | Y Output |
|---------|----------|
| L       | L        |
| H       | Z        |

# MC74VHC1G07, MC74VHC1GT07

## MAXIMUM RATINGS

| Symbol                | Characteristics   | Value  | Unit          |
|-----------------------|---|--|---------------|
| $V_{CC}$              | DC Supply Voltage<br>TSOP-5, SC-88A (NLV)<br>SC-74A, SC-88A, UDFN6, SOT-553, SOT-953  | -0.5 to +7.0<br>-0.5 to +6.5                           | V             |
| $V_{IN}$              | DC Input Voltage<br>TSOP-5, SC-88A (NLV)<br>SC-74A, SC-88A, UDFN6, SOT-553, SOT-953   | -0.5 to +7.0<br>-0.5 to +6.5                           | V             |
| $V_{OUT}$             | DC Output Voltage<br>TSOP-5, SC-88A (NLV)<br>Active-Mode (High or Low State)<br>Tri-State Mode (Note 1)<br>Power-Down Mode ( $V_{CC} = 0$ V)                    | -0.5 to $V_{CC} + 0.5$<br>-0.5 to +7.0<br>-0.5 to +7.0 | V             |
|                       | DC Output Voltage<br>SC-74A, SC-88A, UDFN6, SOT-553, SOT-953<br>Active-Mode (High or Low State)<br>Tri-State Mode (Note 1)<br>Power-Down Mode ( $V_{CC} = 0$ V) | -0.5 to $V_{CC} + 0.5$<br>-0.5 to +6.5<br>-0.5 to +6.5 | V             |
| $I_{IK}$              | DC Input Diode Current<br>$V_{IN} < GND$  | -20  | mA            |
| $I_{OK}$              | DC Output Diode Current<br>$V_{OUT} < GND$  | -20  | mA            |
| $I_{OUT}$             | DC Output Source/Sink Current   | $\pm 25$   | mA            |
| $I_{CC}$ or $I_{GND}$ | DC Supply Current per Supply Pin or Ground Pin  | $\pm 50$   | mA            |
| $T_{STG}$             | Storage Temperature Range   | -65 to +150  | $^{\circ}C$   |
| $T_L$                 | Lead Temperature, 1 mm from Case for 10 secs  | 260  | $^{\circ}C$   |
| $T_J$                 | Junction Temperature Under Bias   | +150   | $^{\circ}C$   |
| $\theta_{JA}$         | Thermal Resistance (Note 2)<br>SC-88A<br>SC-74A<br>SOT-553<br>SOT-953<br>UDFN6  | 377<br>320<br>324<br>254<br>154                        | $^{\circ}C/W$ |
| $P_D$                 | Power Dissipation in Still Air<br>SC-88A<br>SC-74A<br>SOT-553<br>SOT-953<br>UDFN6   | 332<br>390<br>386<br>491<br>812                        | mW            |
| MSL                   | Moisture Sensitivity  | Level 1  | -             |
| $F_R$                 | Flammability Rating<br>Oxygen Index: 28 to 34   | UL 94 V-0 @ 0.125 in                                   | -             |
| $V_{ESD}$             | ESD Withstand Voltage (Note 3)<br>Human Body Model<br>Charged Device Model  | 2000<br>1000   | V             |
| $I_{Latchup}$         | Latchup Performance (Note 4)  | $\pm 100$  | mA            |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

# MC74VHC1G07, MC74VHC1GT07

## RECOMMENDED OPERATING CONDITIONS

| Symbol                          | Characteristics   | Min | Max             | Unit |
|---------------------------------|---|-----|-----------------|------|
| V <sub>CC</sub>                 | Positive DC Supply Voltage  | 2.0 | 5.5             | V    |
| V <sub>IN</sub>                 | DC Input Voltage  | 0   | 5.5             | V    |
| V <sub>OUT</sub>                | DC Output Voltage TSOP-5, SC-88A (NLV)  | 0   | V <sub>CC</sub> | V    |
|                                 | DC Output Voltage SC-74A, SC-88A, UDFN6, SOT-553, SOT-953<br>Active-Mode (High or Low State)<br>Tri-State Mode (Note 1)<br>Power-Down Mode (V <sub>CC</sub> = 0 V)                                      | 0   | V <sub>CC</sub> |      |
|                                 |   | 0   | 5.5             |      |
| T <sub>A</sub>                  | Operating Temperature Range   | -55 | +125            | °C   |
| t <sub>r</sub> , t <sub>f</sub> | Input Rise and Fall Time TSOP-5, SC-88A (NLV)<br>V <sub>CC</sub> = 3.0 V to 3.6 V<br>V <sub>CC</sub> = 4.5 V to 5.5 V   | 0   | 100             | ns/V |
|                                 |   | 0   | 20              |      |
|                                 | Input Rise and Fall Time SC-74A, SC-88A, UDFN6, SOT-553, SOT-953<br>V <sub>CC</sub> = 2.0 V<br>V <sub>CC</sub> = 2.3 V to 2.7 V<br>V <sub>CC</sub> = 3.0 V to 3.6 V<br>V <sub>CC</sub> = 4.5 V to 5.5 V | 0   | 20              |      |
|                                 |   | 0   | 20              |      |
|                                 |   | 0   | 10              |      |
|                                 |   | 0   | 5               |      |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS (MC74VHC1G07)

| Symbol           | Parameter                      | Test Conditions   | V <sub>CC</sub> (V) | T <sub>A</sub> = 25°C |     |       | -40°C ≤ T <sub>A</sub> ≤ 85°C |      | -55°C ≤ T <sub>A</sub> ≤ 125°C |      | Unit |
|------------------|--------------------------------|---|---------------------|-----------------------|-----|-------|-------------------------------|------|--------------------------------|------|------|
|                  |                                |   |                     | Min                   | Typ | Max   | Min                           | Max  | Min                            | Max  |      |
| V <sub>IH</sub>  | High-Level Input Voltage       |   | 2.0                 | 1.5                   | -   | -     | 1.5                           | -    | 1.5                            | -    | V    |
|                  |                                |   | 3.0                 | 2.1                   | -   | -     | 2.1                           | -    | 2.1                            | -    |      |
|                  |                                |   | 4.5                 | 3.15                  | -   | -     | 3.15                          | -    | 3.15                           | -    |      |
|                  |                                |   | 5.5                 | 3.85                  | -   | -     | 3.85                          | -    | 3.85                           | -    |      |
| V <sub>IL</sub>  | Low-Level Input Voltage        |   | 2.0                 | -                     | -   | 0.5   | -                             | 0.5  | -                              | 0.5  | V    |
|                  |                                |   | 3.0                 | -                     | -   | 0.9   | -                             | 0.9  | -                              | 0.9  |      |
|                  |                                |   | 4.5                 | -                     | -   | 1.35  | -                             | 1.35 | -                              | 1.35 |      |
|                  |                                |   | 5.5                 | -                     | -   | 1.65  | -                             | 1.65 | -                              | 1.65 |      |
| V <sub>OL</sub>  | Low-Level Output Voltage       | V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 4 mA<br>I <sub>OL</sub> = 8 mA | 2.0                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  | V    |
|                  |                                |   | 3.0                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  |      |
|                  |                                |   | 4.5                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  |      |
|                  |                                |   | 3.0                 | -                     | -   | 0.36  | -                             | 0.44 | -                              | 0.52 |      |
|                  |                                |   | 4.5                 | -                     | -   | 0.36  | -                             | 0.44 | -                              | 0.52 |      |
| I <sub>IN</sub>  | Input Leakage Current          | V <sub>IN</sub> = 5.5 V or GND  | 2.0 to 5.5          | -                     | -   | ±0.1  | -                             | ±1.0 | -                              | ±1.0 | μA   |
| I <sub>OZ</sub>  | 3-State Output Leakage Current | V <sub>OUT</sub> = 0 V to 5.5 V   | 5.5                 | -                     | -   | ±0.25 | -                             | ±2.5 | -                              | ±2.5 | μA   |
| I <sub>OFF</sub> | Power Off Leakage Current      | V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V   | 0                   | -                     | -   | 1.0   | -                             | 10   | -                              | 10   | μA   |
| I <sub>CC</sub>  | Quiescent Supply Current       | V <sub>IN</sub> = V <sub>CC</sub> or GND  | 5.5                 | -                     | -   | 1.0   | -                             | 20   | -                              | 40   | μA   |

# MC74VHC1G07, MC74VHC1GT07

## DC ELECTRICAL CHARACTERISTICS (MC74VHC1GT07)

| Symbol           | Parameter  | Test Conditions   | V <sub>CC</sub> (V) | T <sub>A</sub> = 25°C |     |       | -40°C ≤ T <sub>A</sub> ≤ 85°C |      | -55°C ≤ T <sub>A</sub> ≤ 125°C |      | Unit |
|------------------|--|---|---------------------|-----------------------|-----|-------|-------------------------------|------|--------------------------------|------|------|
|                  |  |   |                     | Min                   | Typ | Max   | Min                           | Max  | Min                            | Max  |      |
| V <sub>IH</sub>  | High-Level Input Voltage                           |   | 2.0                 | 1.0                   | -   |       | 1.0                           | -    | 1.0                            | -    | V    |
|                  |  |   | 3.0                 | 1.4                   | -   |       | 1.4                           | -    | 1.4                            | -    |      |
|                  |  |   | 4.5                 | 2.0                   | -   |       | 2.0                           | -    | 2.0                            | -    |      |
|                  |  |   | 5.5                 | 2.0                   | -   |       | 2.0                           | -    | 2.0                            | -    |      |
| V <sub>IL</sub>  | Low-Level Input Voltage                            |   | 2.0                 | -                     | -   | 0.28  | -                             | 0.28 | -                              | 0.28 | V    |
|                  |  |   | 3.0                 | -                     | -   | 0.45  | -                             | 0.45 | -                              | 0.45 |      |
|                  |  |   | 4.5                 | -                     | -   | 0.8   | -                             | 0.8  | -                              | 0.8  |      |
|                  |  |   | 5.5                 | -                     | -   | 0.8   | -                             | 0.8  | -                              | 0.8  |      |
| V <sub>OL</sub>  | Low-Level Output Voltage                           | V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 4 mA<br>I <sub>OL</sub> = 8 mA | 2.0                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  | V    |
|                  |  |   | 3.0                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  |      |
|                  |  |   | 4.5                 | -                     | 0.0 | 0.1   | -                             | 0.1  | -                              | 0.1  |      |
|                  |  |   | 3.0                 | -                     | -   | 0.36  | -                             | 0.44 | -                              | 0.52 |      |
|                  |  |   | 4.5                 | -                     | -   | 0.36  | -                             | 0.44 | -                              | 0.52 |      |
| I <sub>IN</sub>  | Input Leakage Current                              | V <sub>IN</sub> = 5.5 V or GND  | 2.0 to 5.5          | -                     | -   | ±0.1  | -                             | ±1.0 | -                              | ±1.0 | μA   |
| I <sub>OZ</sub>  | 3-State Output Leakage Current                     | V <sub>OUT</sub> = 0 V to 5.5 V   | 5.5                 | -                     | -   | ±0.25 | -                             | ±2.5 | -                              | ±2.5 | μA   |
| I <sub>OFF</sub> | Power Off Leakage Current                          | V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V   | 0                   | -                     | -   | 1.0   | -                             | 10   | -                              | 10   | μA   |
| I <sub>CC</sub>  | Quiescent Supply Current                           | V <sub>IN</sub> = V <sub>CC</sub> or GND  | 5.5                 | -                     | -   | 1.0   | -                             | 20   | -                              | 40   | μA   |
| I <sub>CCT</sub> | Increase in Quiescent Supply Current per Input Pin | One Input: V <sub>IN</sub> = 3.4 V; Other Input at V <sub>CC</sub> or GND   | 5.5                 | -                     | -   | 1.35  | -                             | 1.5  | -                              | 1.65 | mA   |

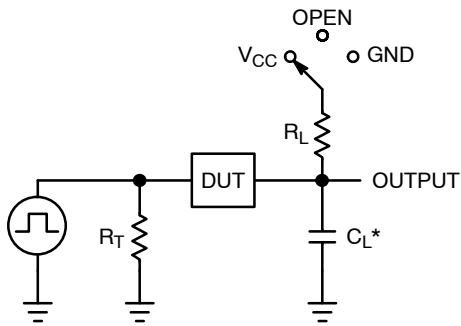
## AC ELECTRICAL CHARACTERISTICS

| Symbol           | Parameter                                   | Conditions                     | V <sub>CC</sub> (V) | T <sub>A</sub> = 25°C |     |      | -40°C ≤ T <sub>A</sub> ≤ 85°C |      | -55°C ≤ T <sub>A</sub> ≤ 125°C |       | Unit |
|------------------|---|--------------------------------|---------------------|-----------------------|-----|------|-------------------------------|------|--------------------------------|-------|------|
|                  |   |                                |                     | Min                   | Typ | Max  | Min                           | Max  | Min                            | Max   |      |
| t <sub>pZL</sub> | Propagation Delay, A to Y (Figures 3 and 4) | C <sub>L</sub> = 15 pF         | 3.0 to 3.6          | -                     | 5.0 | 7.1  | -                             | 8.5  | -                              | 10.0  | ns   |
|                  |   |                                |                     | -                     | 7.5 | 10.6 | -                             | 12.0 | -                              | 14.5  |      |
|                  |   | C <sub>L</sub> = 50 pF         | 4.5 to 5.5          | -                     | 3.8 | 5.5  | -                             | 6.5  | -                              | 8.0   |      |
|                  |   |                                |                     | -                     | 5.3 | 7.5  | -                             | 8.5  | -                              | 10.0  |      |
| t <sub>pLZ</sub> | Propagation Delay, A to Y (Figures 3 and 4) | C <sub>L</sub> = 15 pF         | 3.0 to 3.6          | -                     | 6.5 | 9.7  | -                             | 11.5 | -                              | 12.5  | ns   |
|                  |   |                                |                     | -                     | 7.5 | 10.6 | -                             | 15.0 | -                              | 14.5  |      |
|                  |   | C <sub>L</sub> = 50 pF         | 4.5 to 5.5          | -                     | 4.8 | 6.8  | -                             | 8.0  | -                              | 9.0   |      |
|                  |   |                                |                     | -                     | 5.3 | 7.5  | -                             | 10.0 | -                              | 120.0 |      |
| C <sub>IN</sub>  | Input Capacitance                           |                                |                     | -                     | 4.0 | 10   | -                             | 10   | -                              | 10    | pF   |
| C <sub>OUT</sub> | Output Capacitance                          | Output in High Impedance State |                     | -                     | 6.0 | -    | -                             | -    | -                              | -     | pF   |

|                 |  |   |    |
|-----------------|--|---|----|
| C <sub>PD</sub> | Power Dissipation Capacitance (Note 5) | <b>Typical @ 25°C, V<sub>CC</sub> = 5.0 V</b> | pF |
|                 |  | 8.0   |    |

5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

# MC74VHC1G07, MC74VHC1GT07

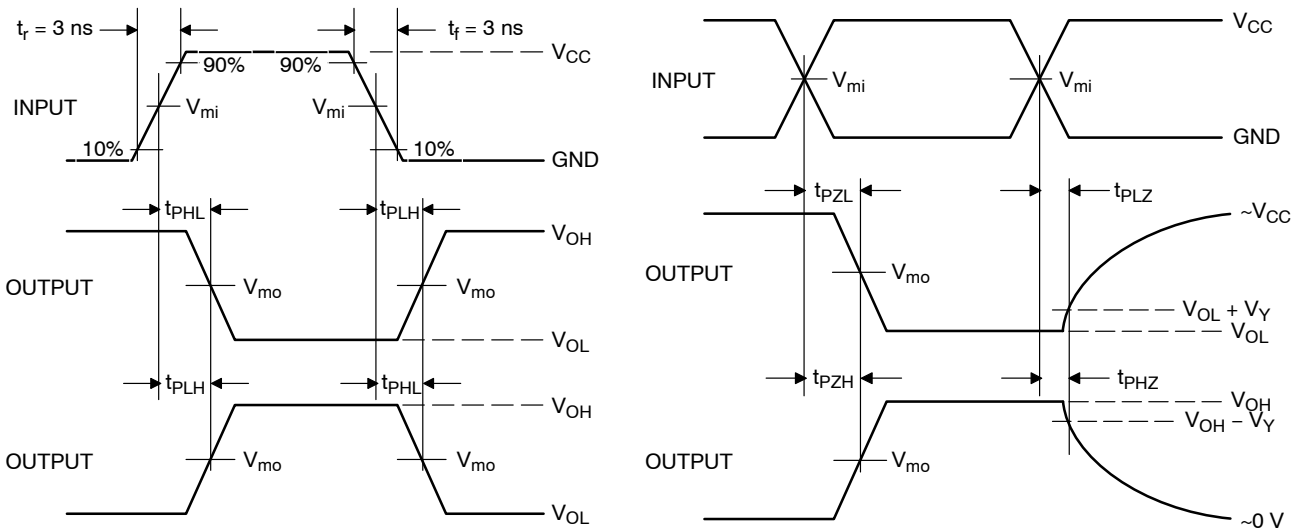


$C_L$  includes probe and jig capacitance  
 $R_T$  is  $Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )  
 $f = 1$  MHz

**Figure 3. Test Circuit**

| Test                | Switch Position | $C_L$ , pF                   | $R_L$ , $\Omega$ |
|---------------------|-----------------|------------------------------|------------------|
| $t_{PLH} / t_{PHL}$ | Open            | See AC Characteristics Table | X                |
| $t_{PLZ} / t_{PZL}$ | $V_{CC}$        |                              | 1 k              |
| $t_{PHZ} / t_{PZH}$ | GND             |                              | 1 k              |

X = Don't Care



**Figure 4. Switching Waveforms**

| $V_{CC}$ , V | $V_{mi}$ , V | $V_{mo}$ , V          |   | $V_Y$ , V |
|--------------|--------------|-----------------------|---|-----------|
|              |              | $t_{PLH}$ , $t_{PHL}$ | $t_{PZL}$ , $t_{PLZ}$ , $t_{PZH}$ , $t_{PHZ}$ |           |
| 3.0 to 3.6   | $V_{CC}/2$   | $V_{CC}/2$            | $V_{CC}/2$                                    | 0.3       |
| 4.5 to 5.5   | $V_{CC}/2$   | $V_{CC}/2$            | $V_{CC}/2$                                    | 0.3       |

# MC74VHC1G07, MC74VHC1GT07

## ORDERING INFORMATION

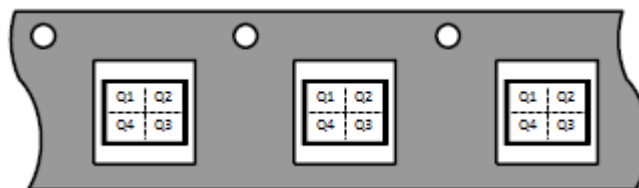
| Device                                 | Packages                | Specific Device Code | Pin 1 Orientation<br>(See below) | Shipping <sup>†</sup> |
|--|-------------------------|----------------------|----------------------------------|-----------------------|
| MC74VHC1G07DFT1G                       | SC-88A                  | V7                   | Q2                               | 3000 / Tape & Reel    |
| MC74VHC1G07DFT2G                       | SC-88A                  | V7                   | Q4                               | 3000 / Tape & Reel    |
| NLVVHC1G07DFT1G*                       | SC-88A                  | V7                   | Q2                               | 3000 / Tape & Reel    |
| NLVVHC1G07DFT2G*                       | SC-88A                  | V7                   | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07DFT1G<br>(In Development)  | SC-88A                  | TBD                  | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07DFT2G<br>(In Development)  | SC-88A                  | TBD                  | Q2                               | 3000 / Tape & Reel    |
| MC74VHC1G07DBVT1G                      | SC-74A                  | V7                   | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07DBVT1G<br>(In Development) | SC-74A                  | TBD                  | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1G07DTT1G                       | TSOP-5                  | V7                   | Q4                               | 3000 / Tape & Reel    |
| NL17VHC1G07DTT1G                       | TSOP-5                  | H7                   | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07DTT1G<br>(In Development)  | TSOP-5                  | TBD                  | Q4                               | 3000 / Tape & Reel    |
| NLV74VHC1G07DTT1G*                     | TSOP-5                  | V7                   | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1G07XV5T2G<br>(In Development)  | SOT-553                 | TBD                  | Q4                               | 4000 / Tape & Reel    |
| MC74VHC1GT07XV5T2G<br>(In Development) | SOT-553                 | TBD                  | Q4                               | 4000 / Tape & Reel    |
| MC74VHC1G07P5T5G<br>(In Development)   | SOT-953                 | TBD                  | Q2                               | 8000 / Tape & Reel    |
| MC74VHC1GT07P5T5G<br>(In Development)  | SOT-953                 | TBD                  | Q2                               | 8000 / Tape & Reel    |
| MC74VHC1G07MU1TCG<br>(In Development)  | UDFN6, 1.45 x 1.0, 0.5P | TBD                  | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07MU1TCG<br>(In Development) | UDFN6, 1.45 x 1.0, 0.5P | TBD                  | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1G07MU2TCG<br>(In Development)  | UDFN6, 1.2 x 1.0, 0.4P  | J                    | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1G07MU3TCG<br>(In Development)  | UDFN6, 1.0 x 1.0, 0.35P | TBD                  | Q4                               | 3000 / Tape & Reel    |
| MC74VHC1GT07MU3TCG<br>(In Development) | UDFN6, 1.0 x 1.0, 0.35P | TBD                  | Q4                               | 3000 / Tape & Reel    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

### Pin 1 Orientation in Tape and Reel

Direction of Feed

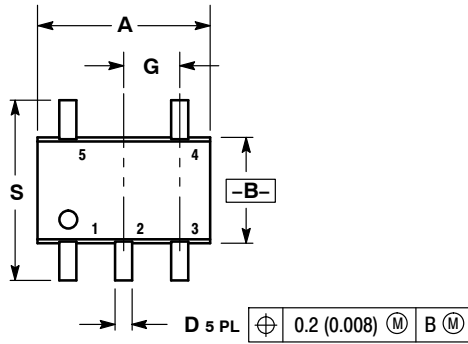




# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

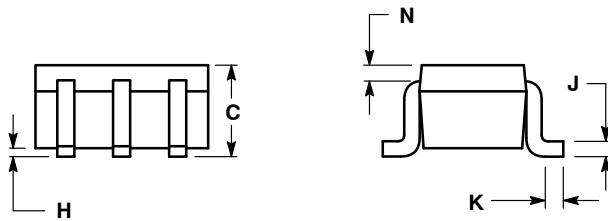
SC-88A (SC-70-5/SOT-353)  
CASE 419A-02  
ISSUE L



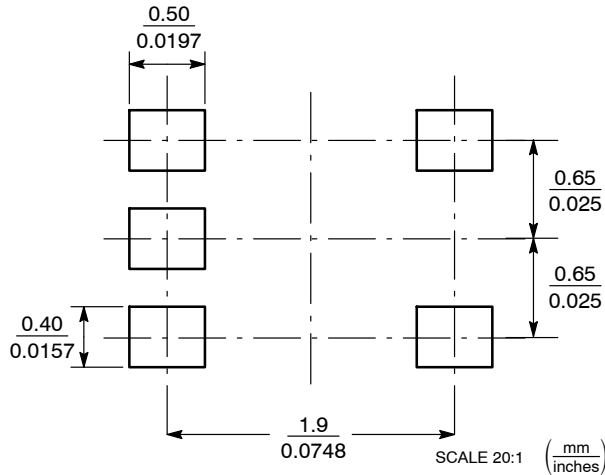
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | INCHES    |       | MILLIMETERS |      |
|-----|-----------|-------|-------------|------|
|     | MIN       | MAX   | MIN         | MAX  |
| A   | 0.071     | 0.087 | 1.80        | 2.20 |
| B   | 0.045     | 0.053 | 1.15        | 1.35 |
| C   | 0.031     | 0.043 | 0.80        | 1.10 |
| D   | 0.004     | 0.012 | 0.10        | 0.30 |
| G   | 0.026 BSC |       | 0.65 BSC    |      |
| H   | ---       | 0.004 | ---         | 0.10 |
| J   | 0.004     | 0.010 | 0.10        | 0.25 |
| K   | 0.004     | 0.012 | 0.10        | 0.30 |
| N   | 0.008 REF |       | 0.20 REF    |      |
| S   | 0.079     | 0.087 | 2.00        | 2.20 |



### SOLDER FOOTPRINT\*

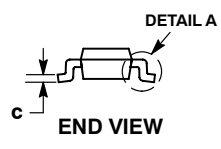
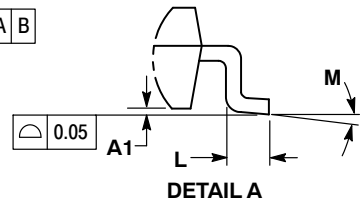
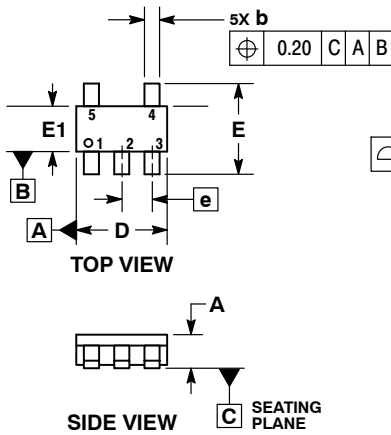


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

### SC-74A CASE 318BQ ISSUE B

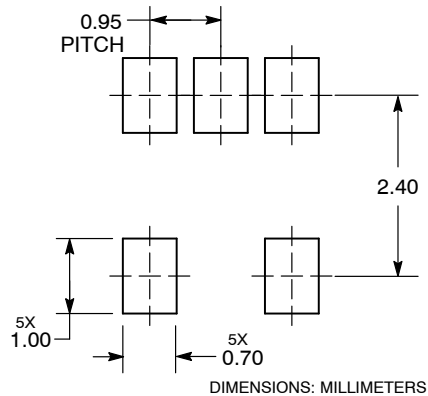


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.90        | 1.10 |
| A1  | 0.01        | 0.10 |
| b   | 0.25        | 0.50 |
| c   | 0.10        | 0.26 |
| D   | 2.85        | 3.15 |
| E   | 2.50        | 3.00 |
| E1  | 1.35        | 1.65 |
| e   | 0.95 BSC    |      |
| L   | 0.20        | 0.60 |
| M   | 0° 10°      |      |

### RECOMMENDED SOLDERING FOOTPRINT\*



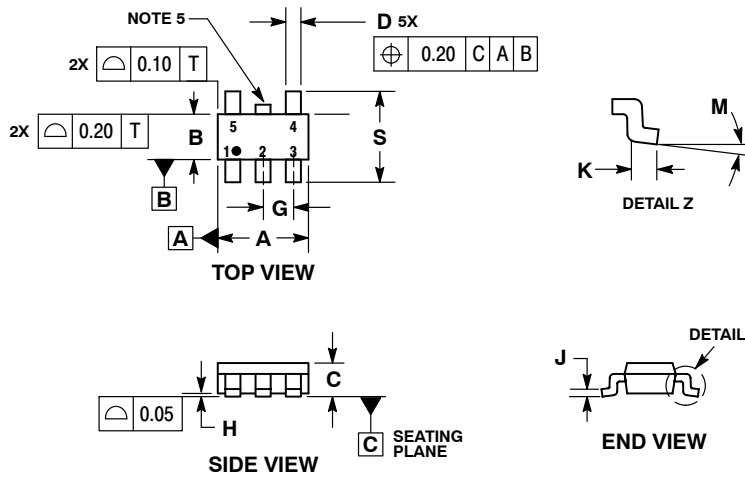
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

**TSOP-5**  
CASE 483  
ISSUE N

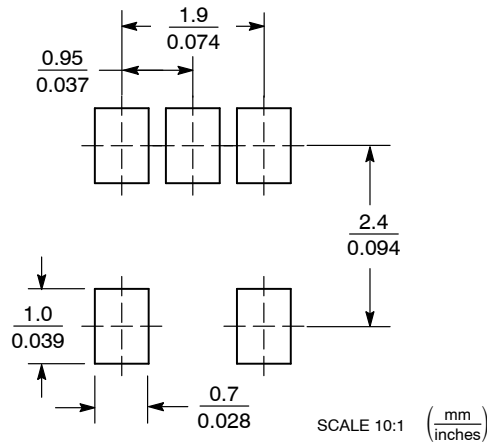


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| MILLIMETERS |          |      |
|-------------|----------|------|
| DIM         | MIN      | MAX  |
| A           | 2.85     | 3.15 |
| B           | 1.35     | 1.65 |
| C           | 0.90     | 1.10 |
| D           | 0.25     | 0.50 |
| G           | 0.95 BSC |      |
| H           | 0.01     | 0.10 |
| J           | 0.10     | 0.26 |
| K           | 0.20     | 0.60 |
| M           | 0° 10°   |      |
| S           | 2.50     | 3.00 |

### SOLDERING FOOTPRINT\*

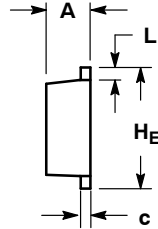
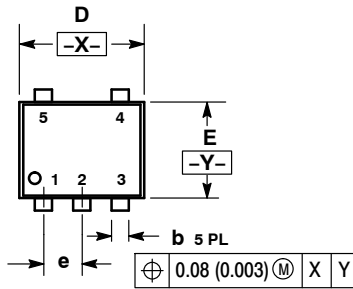


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

### SOT-553, 5 LEAD CASE 463B ISSUE C

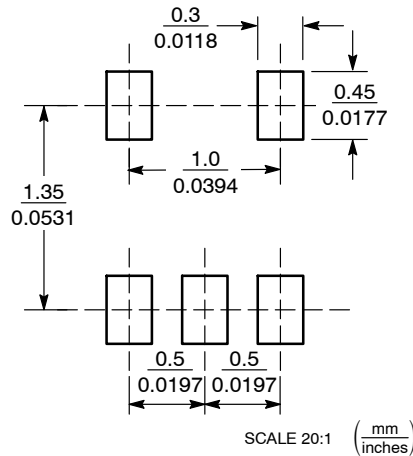


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| DIM | MILLIMETERS |      |      | INCHES    |       |       |
|-----|-------------|------|------|-----------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN       | NOM   | MAX   |
| A   | 0.50        | 0.55 | 0.60 | 0.020     | 0.022 | 0.024 |
| b   | 0.17        | 0.22 | 0.27 | 0.007     | 0.009 | 0.011 |
| c   | 0.08        | 0.13 | 0.18 | 0.003     | 0.005 | 0.007 |
| D   | 1.55        | 1.60 | 1.65 | 0.061     | 0.063 | 0.065 |
| E   | 1.15        | 1.20 | 1.25 | 0.045     | 0.047 | 0.049 |
| e   | 0.50 BSC    |      |      | 0.020 BSC |       |       |
| L   | 0.10        | 0.20 | 0.30 | 0.004     | 0.008 | 0.012 |
| HE  | 1.55        | 1.60 | 1.65 | 0.061     | 0.063 | 0.065 |

### SOLDERING FOOTPRINT\*

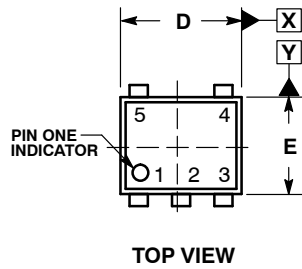


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

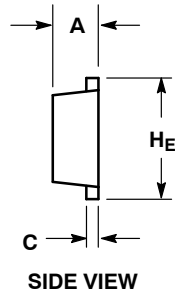
# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

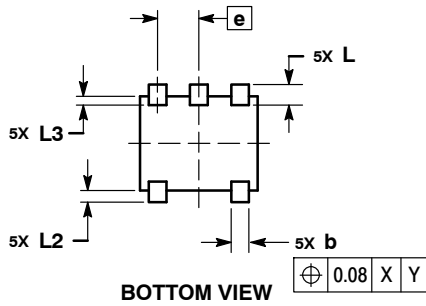
**SOT-953**  
CASE 527AE  
ISSUE E



TOP VIEW



SIDE VIEW



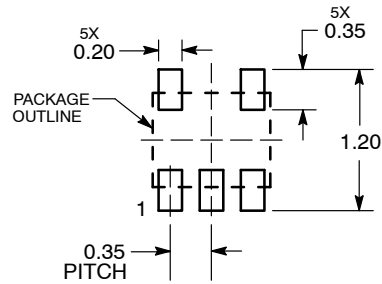
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| MILLIMETERS    |           |      |      |
|----------------|-----------|------|------|
| DIM            | MIN       | NOM  | MAX  |
| A              | 0.34      | 0.37 | 0.40 |
| b              | 0.10      | 0.15 | 0.20 |
| C              | 0.07      | 0.12 | 0.17 |
| D              | 0.95      | 1.00 | 1.05 |
| E              | 0.75      | 0.80 | 0.85 |
| e              | 0.35 BSC  |      |      |
| H <sub>E</sub> | 0.95      | 1.00 | 1.05 |
| L              | 0.175 REF |      |      |
| L2             | 0.05      | 0.10 | 0.15 |
| L3             | ---       | ---  | 0.15 |

### SOLDERING FOOTPRINT\*



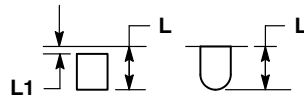
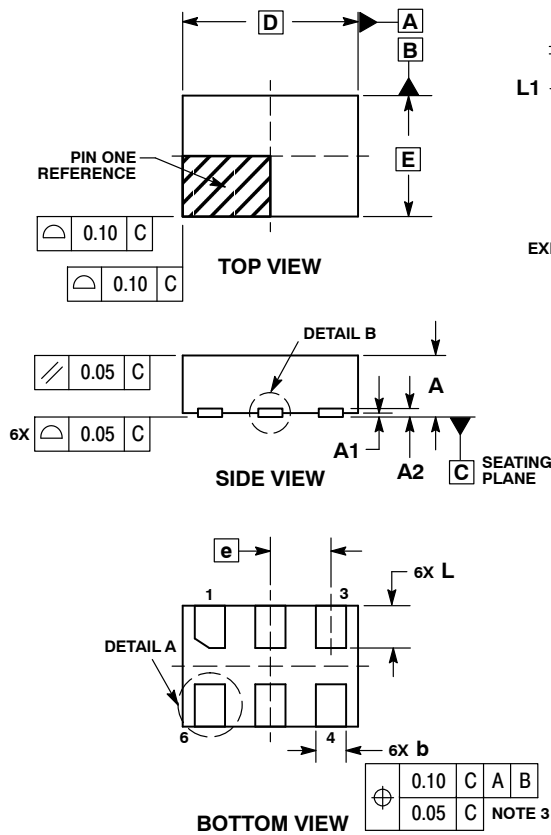
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

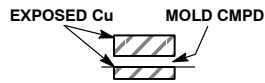
# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P  
CASE 517AQ  
ISSUE O



**DETAIL A**  
OPTIONAL  
CONSTRUCTIONS



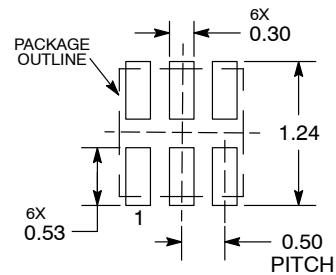
**DETAIL B**  
OPTIONAL  
CONSTRUCTIONS

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

| MILLIMETERS |      |      |
|-------------|------|------|
| DIM         | MIN  | MAX  |
| A           | 0.45 | 0.55 |
| A1          | 0.00 | 0.05 |
| A2          | 0.07 | REF  |
| b           | 0.20 | 0.30 |
| D           | 1.45 | BSC  |
| E           | 1.00 | BSC  |
| e           | 0.50 | BSC  |
| L           | 0.30 | 0.40 |
| L1          | ---  | 0.15 |

### MOUNTING FOOTPRINT



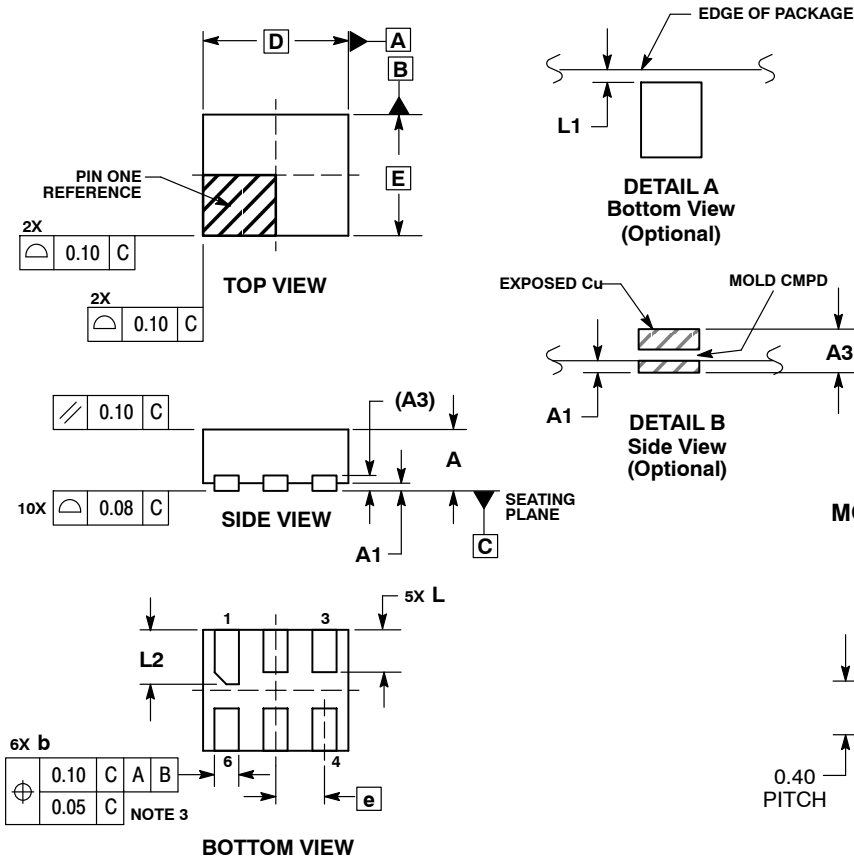
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P  
CASE 517AA-01  
ISSUE D

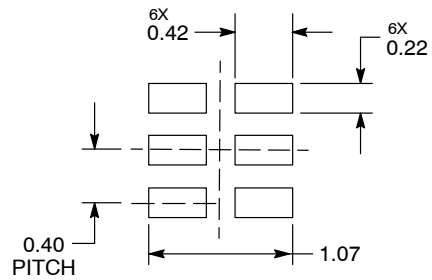


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS |       |      |
|-------------|-------|------|
| DIM         | MIN   | MAX  |
| A           | 0.45  | 0.55 |
| A1          | 0.00  | 0.05 |
| A3          | 0.127 | REF  |
| b           | 0.15  | 0.25 |
| D           | 1.20  | BSC  |
| E           | 1.00  | BSC  |
| e           | 0.40  | BSC  |
| L           | 0.30  | 0.40 |
| L1          | 0.00  | 0.15 |
| L2          | 0.40  | 0.50 |

**MOUNTING FOOTPRINT\***



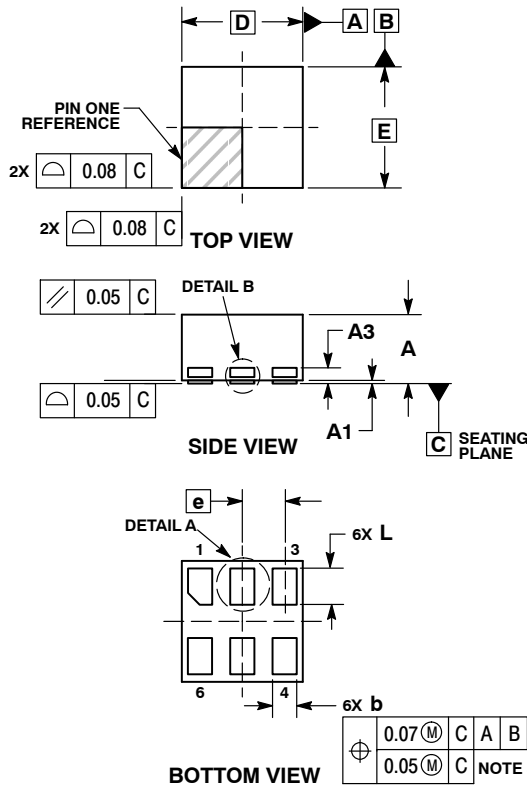
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74VHC1G07, MC74VHC1GT07

## PACKAGE DIMENSIONS

UDFN6, 1x1, 0.35P  
CASE 517BX  
ISSUE O

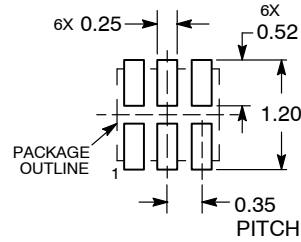


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

| MILLIMETERS |          |      |
|-------------|----------|------|
| DIM         | MIN      | MAX  |
| A           | 0.50     | 0.65 |
| A1          | 0.00     | 0.05 |
| A3          | 0.13 REF |      |
| b           | 0.17     | 0.23 |
| D           | 1.00 BSC |      |
| E           | 1.00 BSC |      |
| e           | 0.35     |      |
| L           | 0.20     | 0.40 |
| L1          | ---      | 0.15 |
| L3          | 0.26     | 0.33 |

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSION: MILLIMETERS

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